

AMENDMENT TO THE CLAIMS

This listing of claims will replace all prior versions of claims in the application:

LISTING OF CLAIMS:

1. (CURRENTLY AMENDED) A system for lapping a head, comprising:
 - (a) a wafer including at least one head each having an electrical lapping guide (ELG), a plurality of wafer contacts in electrical communication with the ELG, and a closure formed thereon defining a slot in which the wafer contacts are positioned;
 - (b) a lapping cable coupled to a testing device, the lapping cable including a plurality of lapping cable contacts; and
 - (c) an adapter including a plurality of adapter contacts in electrical communication with the lapping cable contacts;
 - (d) wherein the adapter contacts are removably positionable in electrical communication with the wafer contacts during a lapping process.
2. (ORIGINAL) The system as recited in claim 1, wherein the adapter is constructed from a polyimide material.
3. (PREVIOUSLY PRESENTED) The system as recited in claim 1, wherein the adapter includes a pair of holes formed therein for coupling with a pair of holes formed in the lapping cable via a pair of alignment pins.
4. (ORIGINAL) The system as recited in claim 1, wherein the adapter includes at least one guide for being removably positioned in a slot defined by closures of adjacent heads formed on the wafer.

5. (ORIGINAL) The system as recited in claim 1, wherein the adapter contacts are slidably coupled to the adapter.
6. (ORIGINAL) The system as recited in claim 1, wherein the adapter contacts each include a first portion in electrical communication with one of the lapping cable contacts and a second portion in electrical communication with one of the wafer contacts.
7. (ORIGINAL) The system as recited in claim 6, wherein the first portion of each adapter contact is larger than the second portion of each adapter contact.
8. (ORIGINAL) The system as recited in claim 7, wherein the first portion of each adapter contact has a diameter larger than that of the second portion of each adapter contact.
9. (ORIGINAL) The system as recited in claim 6, wherein the adapter includes a recess for preventing contact with the wafer during the lapping process.

10-13. (CANCEL)

14. (ORIGINAL) An apparatus for use with a wafer including at least one head each having an electrical lapping guide (ELG), a plurality of wafer contacts in electrical communication with the ELG, and a closure formed thereon defining a slot in which the wafer contacts are positioned, and a lapping cable coupled to a testing device, the lapping cable including a plurality of lapping cable contacts; the apparatus comprising: an adapter including a plurality of adapter contacts in electrical communication with the lapping cable contacts, wherein the adapter contacts are removably positionable in electrical communication with the wafer contacts during a lapping process.

15. (CANCEL)

16. (CURRENTLY AMENDED) An adapter including a plurality of adapter contacts adapted for electrical communication with a plurality of lapping cable contacts of a lapping cable, wherein the adapter contacts are removably positionable in electrical communication with a plurality of wafer contacts of a wafer during a lapping process, the wafer including at least one head each having an electrical lapping guide (ELG), the wafer contacts being in electrical communication with the ELG, and a closure extending from a surface in which the wafer contacts are positioned.

17-19. (CANCEL)

20. (CURRENTLY AMENDED) A system for lapping a head, comprising:
a wafer including at least one head each having an electrical lapping guide (ELG), the wafer contacts being in electrical communication with the ELG, and a closure extending from a surface in which the wafer contacts are positioned.
(a) a lapping cable coupled to a testing device, the lapping cable including a plurality of lapping cable contacts; and
(b) an adapter including a plurality of adapter contacts in electrical communication with the lapping cable contacts;
(c) wherein the adapter contacts are removably positionable in electrical communication with the contacts on a the wafer during a lapping process.